

IN THE CLAIMS:

Please amend claims 24, 25, 26, and 28 as set forth below. Applicants' note that all claims currently pending in the Application are shown below for clarity.

23. A gate stack, including a non-crystalline metallic silicide film.

Sub F²
① 24. (Twice Amended) A gate stack, including [a crystalline] an amorphous metallic silicide film wherein said metallic silicide film is substantially devoid of silicon clusters.

25. (Twice Amended) A gate stack on a dielectric layered [semiconductor] silicon substrate, comprising:
a polysilicon layer disposed over said dielectric layered [semiconductor] silicon substrate;
a non-crystalline metallic silicide film disposed over said polysilicon layer; and
a dielectric cap on said non-crystalline metallic silicide film.

Sub F³
② 26. (Amended) A gate stack structure comprising a gate stack on a dielectric layered [semiconductor] silicon substrate wherein [said] a gate dielectric layer of said gate stack is substantially devoid of pitting.

27. The gate stack structure of claim 26 wherein said a gate stack includes a non-crystalline metallic silicide film.

Sub F⁵
③ 28. (Twice Amended) The gate stack structure of claim 26 wherein said [a] gate stack includes [a crystalline] an amorphous metallic silicide film substantially devoid of silicon clusters.